

200mW SOD-323 SURFACE MOUNT
Small Outline Gull Wing Lead Plastic Package
High Voltage Switching Diode

Green Product

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
P_D	Power Dissipation	200	mW
V_{RRM}	Maximum Repetitive Reverse Voltage	250	V
T_{STG}	Storage Temperature Range	-65 to +150	$^\circ\text{C}$
T_J	Operating Junction Temperature	+150	$^\circ\text{C}$
$I_{F(AV)}$	Average Rectified Forward Current	200	mA
I_{FSM}	Non-repetitive Peak Forward Current Pulse Width = 1.0 Second	1.0	A
		4.0	A

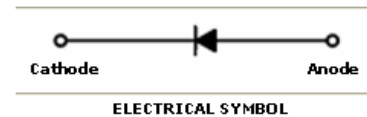
These ratings are limiting values above which the serviceability of the diode may be impaired.



SOD-323 Gull Wing Lead

Specification Features:

- Gull Wing Lead SOD-323 Small Outline Plastic Package
- Surface Device Type Mounting
- RoHS Compliant
- Green EMC
- Matte Tin(Sn) Lead Finish
- Band Indicates Cathode
- Weight: approx. 0.004g

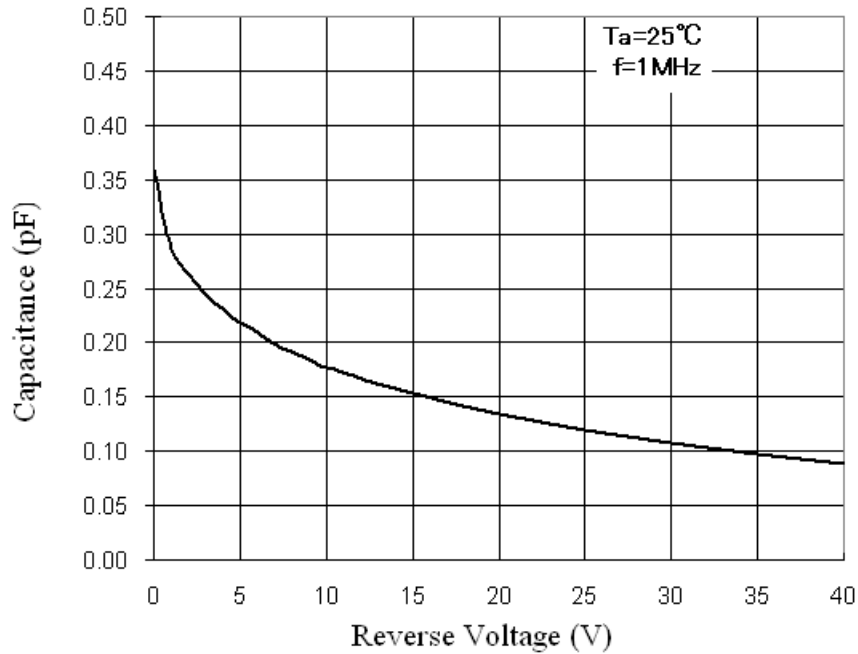
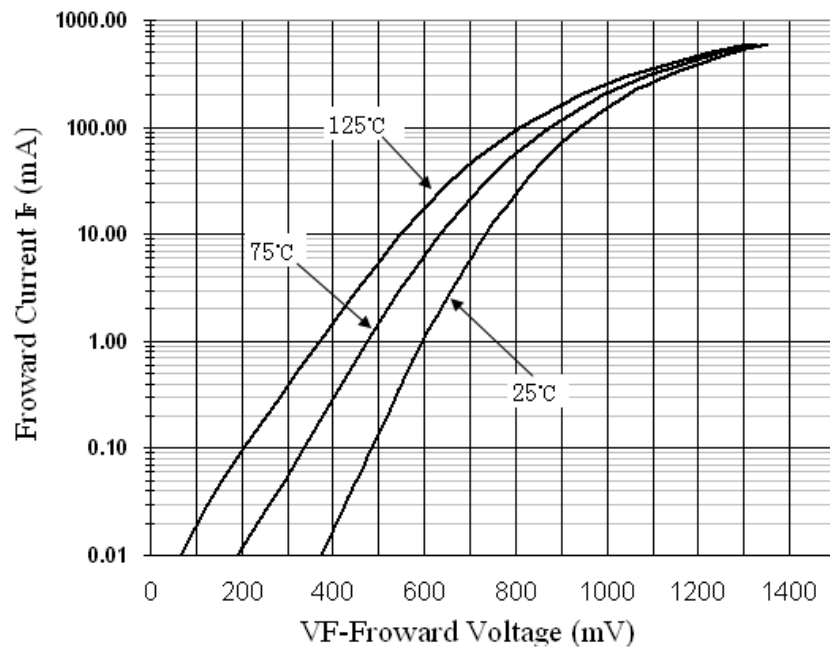


DEVICE MARKING CODE:

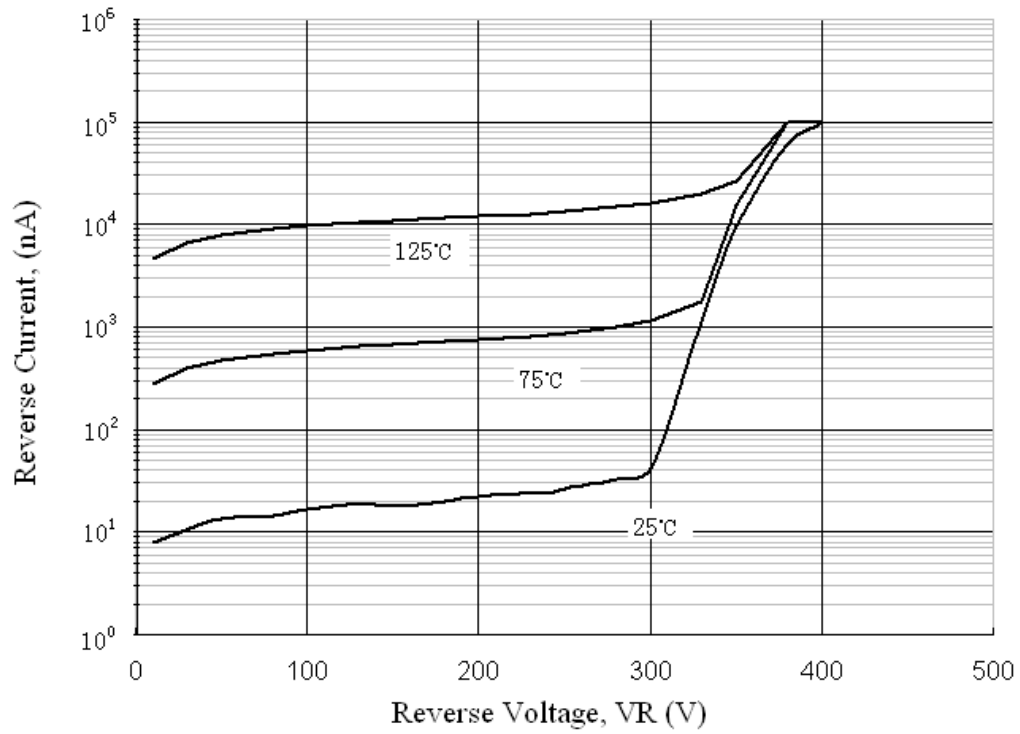
Device Type	Device Marking
BAV19WSG	A8
BAV20WSG	T2
BAV21WSG	T3

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

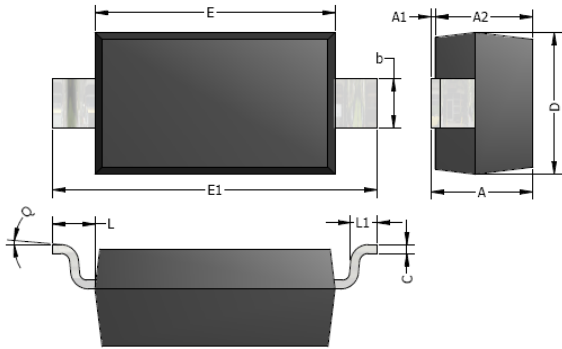
Symbol	Parameter	Test Condition	Limits		Unit	
			Min	Max		
B_V	Breakdown Voltage	BAV19WSG	$I_R=100\mu\text{A}$	120	---	Volts
		BAV20WSG		200	---	Volts
		BAV21WSG		250	---	Volts
I_R	Reverse Leakage Current	BAV19WSG	$V_R=100\text{V}$	---	100	nA
		BAV20WSG	$V_R=150\text{V}$	---	100	nA
		BAV21WSG	$V_R=200\text{V}$	---	100	nA
V_F	Forward Voltage		$I_F=100\text{mA}$	---	1.0	Volts
			$I_F=200\text{mA}$	---	1.25	Volts
T_{RR}	Reverse Recovery Time		$I_F=I_R=30\text{mA}$ $R_L=100\Omega$ $I_{RR}=3\text{mA}$	---	50	nS
C	Capacitance		$V_R=0\text{V}, f=1\text{MHz}$	---	5.0	pF

Typical Performance Characteristics
Total Capacitance

Forward Voltage vs Ambient Temperature


Reverse Current vs Reverse Voltage

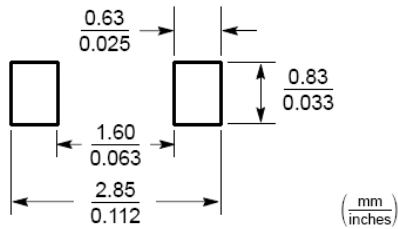


SOD-323 Gull Wing Lead Package Outline



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A2	0.80	0.90	0.031	0.035
b	0.30	0.40	0.012	0.016
c	0.08	0.15	0.003	0.006
D	1.20	1.40	0.047	0.055
E	1.60	1.80	0.063	0.071
E1	2.50	2.70	0.098	0.106
L	0.475 REF.		0.019 REF.	
L1	0.25	0.40	0.010	0.016
θ	0°	8°	0°	8°

Typical Soldering Pattern:



Note:
Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.

NOTICE

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